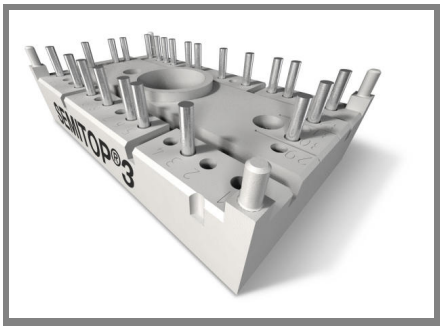
# SK75GB066T




**SEMITOP® 3**

## IGBT Module

**SK75GB066T**

Target Data

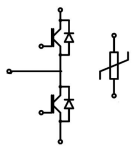
### Features

- Compact design
- One scre mounting
- Heat transfer and isolation trough direct copper bonded aluminium oxide ceramic (DCB)
- Trench IGBT technology
- CAL HD technology FWD
- Integrated NTC temperature sensor

### Typical Applications*

### Remarks

- $V_{isol}$ = 3000V AC,50Hz,1s

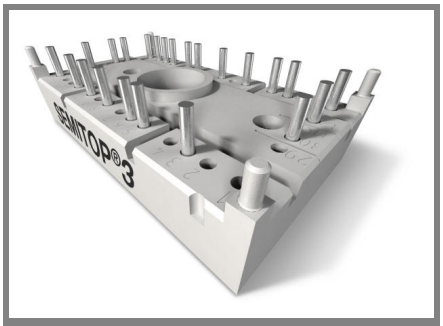


**GB-T**

| **Absolute Maximum Ratings** | | | $T_s$ = 25 °C, unless otherwise specified | |
|---|---|---|---|---|
| **Symbol** | **Conditions** | | **Values** | **Units** |
| **IGBT** | | | | |
| $V_{CES}$ | $T_j$ = 25 °C | | 600 | V |
| $I_C$ | $T_j$ = 175 °C | $T_s$ = 25 °C | 77 | A |
| | | $T_s$ = 70 °C | 60 | A |
| $I_{CRM}$ | $I_{CRM}$= 2 x $I_{Cnom}$ | | 150 | A |
| $V_{GES}$ | | | ± 20 | V |
| $t_{psc}$ | $V_{CC}$ = 360 V; $V_{GE} \leq$ 20 V; $V_{CES}$ < 600 V | $T_j$ = 150 °C | 6 | µs |
| **Inverse Diode** | | | | |
| $I_F$ | $T_j$ = 175 °C | $T_s$ = 25 °C | 62 | A |
| | | $T_s$ = 70 °C | 47 | A |
| $I_{FRM}$ | $I_{FRM}$= 2 x $I_{Fnom}$ | | 150 | A |
| $I_{FSM}$ | $t_p$ = 10 ms; half sine wave | $T_j$ = 150 °C | 395 | A |
| **Module** | | | | |
| $I_{t(RMS)}$ | | | | A |
| $T_{vj}$ | | | -40 ... +175 | °C |
| $T_{stg}$ | | | -40 ... +125 | °C |
| $V_{isol}$ | AC, 1 min. | | 2500 | V |

| **Characteristics** | | | $T_s$ = 25 °C, unless otherwise specified | | | |
|---|---|---|---|---|---|---|
| **Symbol** | **Conditions** | | **min.** | **typ.** | **max.** | **Units** |
| **IGBT** | | | | | | |
| $V_{GE(th)}$ | $V_{GE}$ = $V_{CE}$, $I_C$ = 1,2 mA | | 5 | 5,8 | 6,5 | V |
| $I_{CES}$ | $V_{GE}$ = 0 V, $V_{CE}$ = $V_{CES}$ | $T_j$ = 25 °C | | | 0,0038 | mA |
| | | $T_j$ = 125 °C | | | | mA |
| $I_{GES}$ | $V_{CE}$ = 0 V, $V_{GE}$ = 20 V | $T_j$ = 25 °C | | | 600 | nA |
| | | $T_j$ = 125 °C | | | | nA |
| $V_{CE0}$ | | $T_j$ = 25 °C | | 0,8 | 1,1 | V |
| | | $T_j$ = 150 °C | | 0,7 | 1 | V |
| $r_{CE}$ | $V_{GE}$ = 15 V | $T_j$ = 25°C | | 8 | 10 | mΩ |
| | | $T_j$ = 150°C | | 12,7 | 14 | mΩ |
| $V_{CE(sat)}$ | $I_{Cnom}$ = 75 A, $V_{GE}$ = 15 V | $T_j$ = 25°C$_{chiplev.}$ | | 1,45 | 1,85 | V |
| | | $T_j$ = 150°C$_{chiplev.}$ | | 1,65 | 2,05 | V |
| $C_{ies}$ | $V_{CE}$ = 25, $V_{GE}$ = 0 V | f = 1 MHz | | 4,7 | | nF |
| $C_{oes}$ | | | | 0,3 | | nF |
| $C_{res}$ | | | | 0,145 | | nF |
| $Q_G$ | $V_{GE}$= -7V...+15V | | | 700 | | nC |
| $t_{d(on)}$ | $R_{Gon}$ = 16 Ω<br>di/dt = 2250 A/µs | $V_{CC}$ = 300V<br>$I_C$= 75A<br>$T_j$ = 150 °C<br>$V_{GE}$= -7/+15 V | | 95 | | ns |
| $t_r$ | | | | 50 | | ns |
| $E_{on}$ | | | | 3,1 | | mJ |
| $t_{d(off)}$ | $R_{Goff}$ = 16 Ω<br>di/dt = 2250 A/µs | | | 541 | | ns |
| $t_f$ | | | | 70 | | ns |
| $E_{off}$ | | | | 2,8 | | mJ |
| $R_{th(j-s)}$ | per IGBT | | | 0,94 | | K/W |



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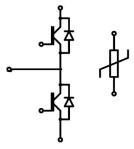


**GB-T**

**Characteristics**

| Symbol | Conditions | | min. | typ. | max. | Units |
|---|---|---|---|---|---|---|
| **Inverse Diode** | | | | | | |
| $V_F = V_{EC}$ | $I_{Fnom}$ = 75 A; $V_{GE}$ = 0 V | $T_j$ = 25 °$C_{chiplev.}$ | | 1,35 | | V |
| | | $T_j$ = 150 °$C_{chiplev.}$ | | 1,31 | | V |
| $V_{F0}$ | | $T_j$ = 25 °C | | | | V |
| | | $T_j$ = 150 °C | | 0,85 | | V |
| $r_F$ | | $T_j$ = 25 °C | | | | mΩ |
| | | $T_j$ = 150 °C | | 7,8 | | mΩ |
| $I_{RRM}$ | $I_F$ = 75 A | $T_j$ = 150 °C | | 60 | | A |
| $Q_{rr}$ | di/dt = 2250 A/µs | | | 6 | | µC |
| $E_{rr}$ | $V_{CC}$= 300V | | | 0,85 | | mJ |
| $R_{th(j-s)D}$ | per diode | | | 1,55 | | K/W |
| $M_s$ | to heat sink | | 2,5 | | 2,75 | Nm |
| w | | | | 60 | | g |
| **Temperature sensor** | | | | | | |
| $R_{100}$ | $T_s$ = 100°C ($R_{25}$=5kΩ) | | | 493±5% | | Ω |

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.

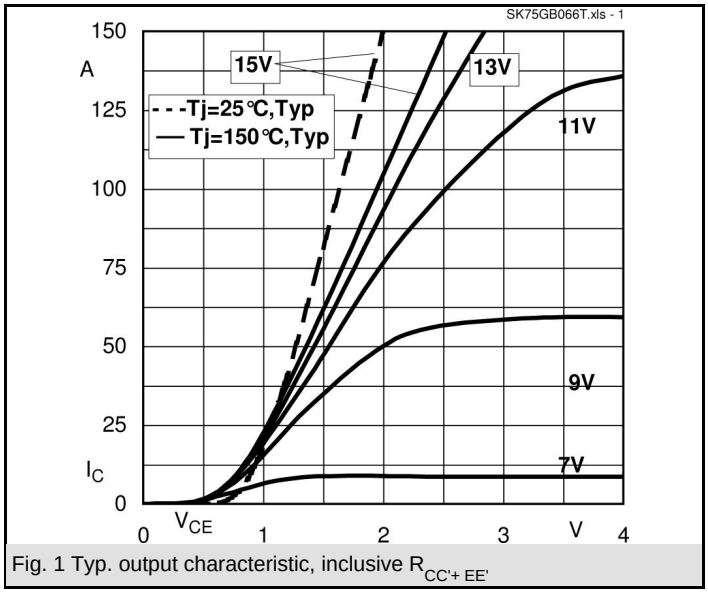



Fig. 1 Typ. output characteristic, inclusive $R_{CC'+EE'}$

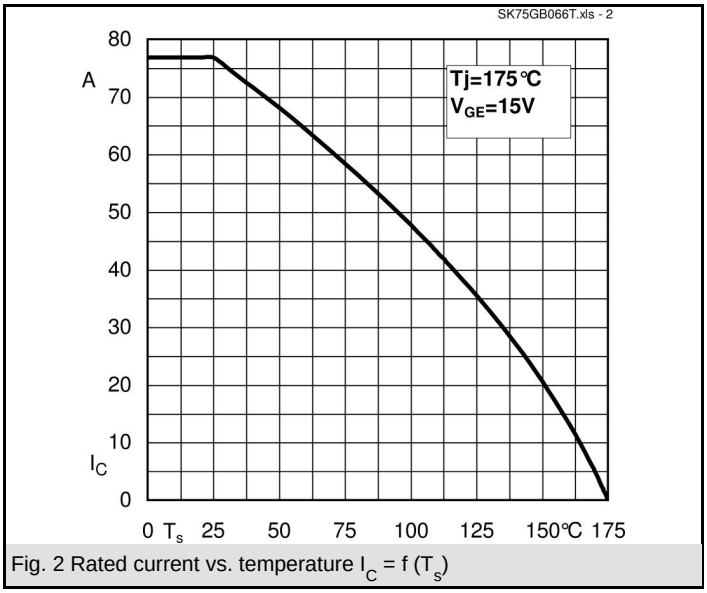



Fig. 2 Rated current vs. temperature $I_C = f(T_s)$

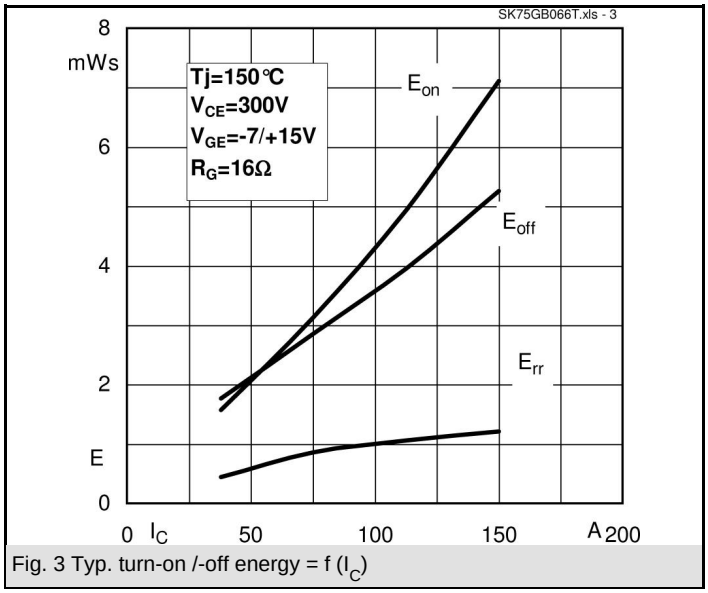



Fig. 3 Typ. turn-on /-off energy = f ($I_C$)

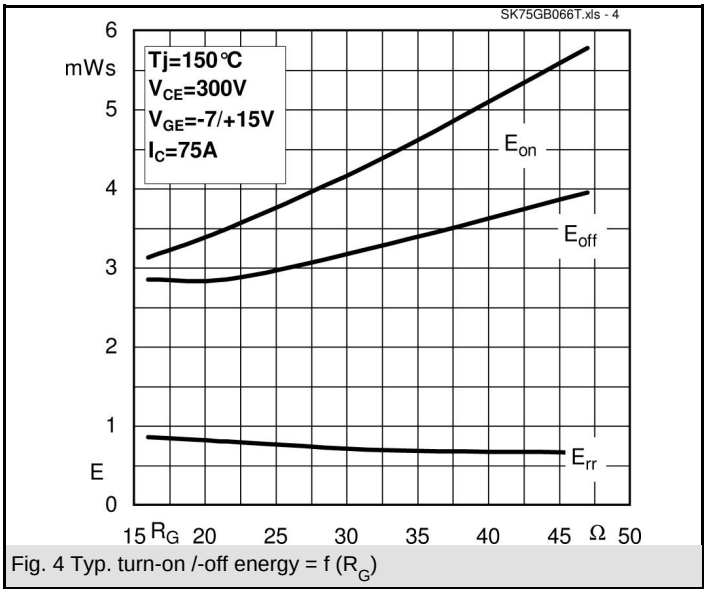



Fig. 4 Typ. turn-on /-off energy = f ($R_G$)

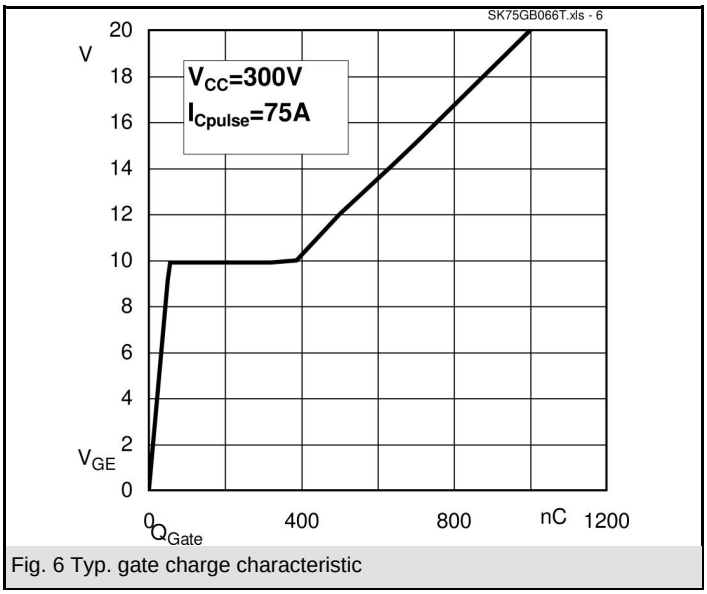



Fig. 6 Typ. gate charge characteristic

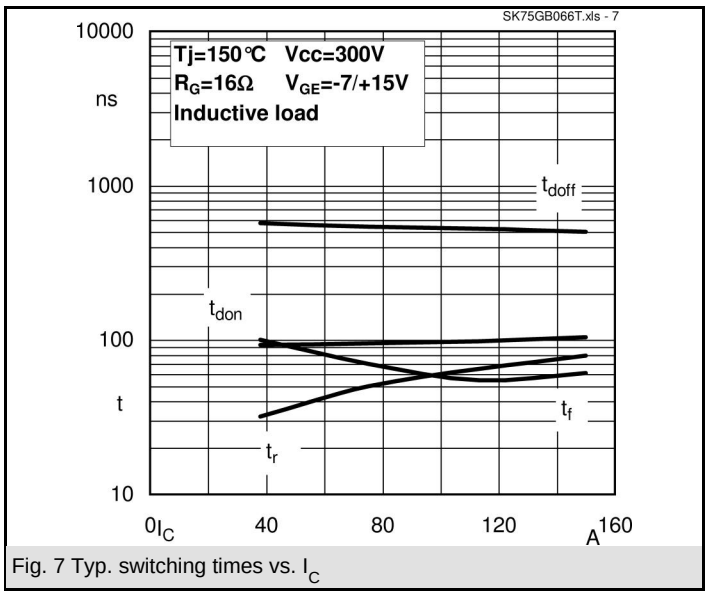



Fig. 7 Typ. switching times vs. $I_C$

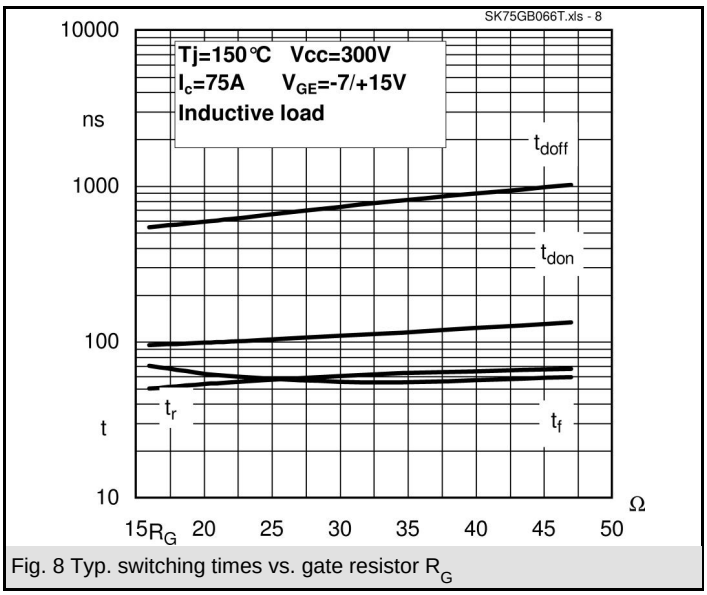



Fig. 8 Typ. switching times vs. gate resistor $R_G$

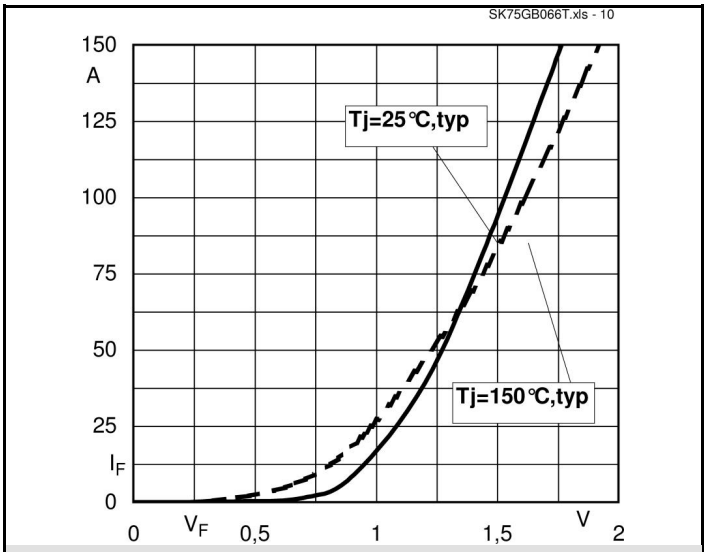
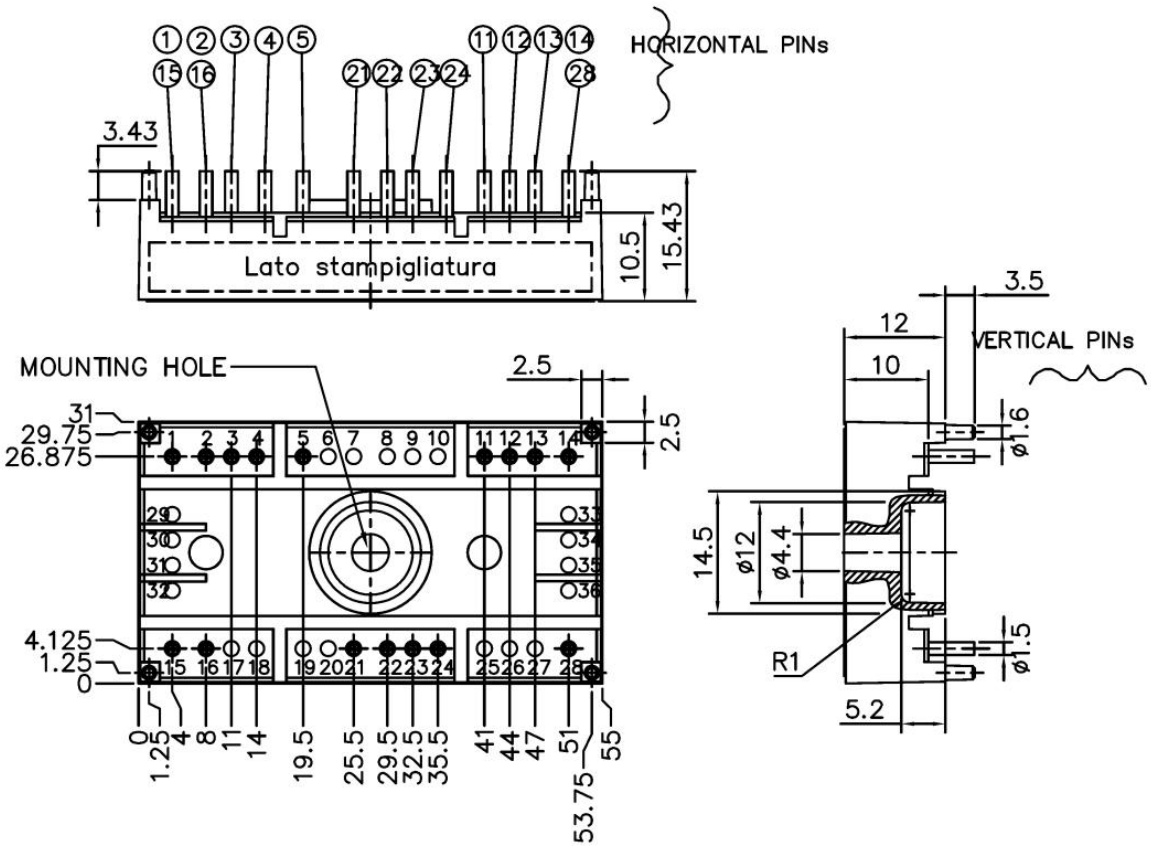


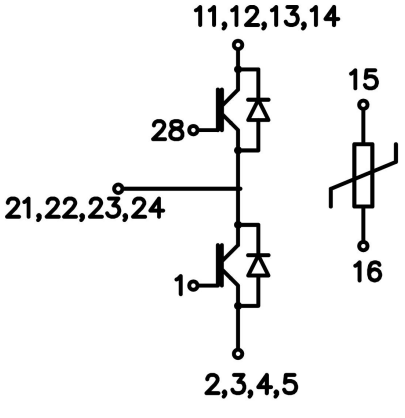

Fig. 10 CAL diode forward characteristic

UL recognized file no. E 63 532




Case T73 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)




Case T 73 GB-T